

# Product Change Notification - KSRA-25BPKT420

#### Date:

27 Jul 2018

**Product Category:** 

32-bit Microcontrollers

#### Affected CPNs:

#### 7

## Notification subject:

CCB 3467 Initial Notice: Qualification of a new lead frame with double ring plating on paddle for selected Atmel products of 58.85K wafer technology available in 48L TQFP (7x7x1.0mm) package at ASE assembly site using palladium coated copper with gold flash (CuPdAu) bond wire

# Notification text:

PCN Status:

Initial notification.

## PCN Type:

Manufacturing Change

# **Microchip Parts Affected:**

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

# **Description of Change:**

Qualification of a new lead frame with double ring plating on paddle for selected Atmel products of 58.85K wafer technology available in 48L TQFP (7x7x1.0mm) package at ASE assembly site using palladium coated copper with gold flash (CuPdAu) bond wire

# Pre Change:

Assembled at ASE Inc. Taiwan (ASE) using a lead frame with single ring plating on paddle palladium coated copper (CuPd) Bond wire

# Post Change:

Assembled at ASE Inc. Taiwan (ASE) using a lead frame with double ring plating on paddle using palladium coated copper with gold flash (CuPdAu) bond wire

# Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	ASE Inc. (ASE)	ASE Inc. (ASE)
Wire material	CuPd	CuPdAu
Die attach material	CRM-1076WA	CRM-1076WA
Molding compound	EME-G631H	EME-G631H
material	EIVIE-G03TH	EME-003TH
Lead frame material	C7025	C7025
Lead frame Surface	Ring	Double Ring

Note: See attached lead frame comparison

#### Impacts to Data Sheet:

None or list the changes that will be identified in the data sheet.

Change Impact:

None

# Reason for Change:

To improve on-time delivery performance and qualify a new lead frame with double ring plating on paddle.

# **Change Implementation Status:**

In Progress

**Estimated Qualification Completion Date :** 



#### December 2018

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

#### Time Table Summary:

	July 2018					December 2018					
Workweek	27	28	29	30	31	>	48	49	50	51	52
Initial PCN Issue Date				Х							
Qual Report Availability											Х
Final PCN Issue Date											Х

#### Method to Identify Change:

Traceability code

#### Qualification Plan:

Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Plan.

#### **Revision History:**

July 27, 2018: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products

#### Attachment(s):

PCN\_KSRA-25BPKT420\_Qual\_Plan.pdf Lead Frame Pre and Post Change Comparison.pdf

Please contact your local <u>Microchip sales office</u> with questions or concerns regarding this notification.

#### Terms and Conditions:

If you wish to change your product/process change notification (PCN) profile please log on to our website at <u>http://www.microchip.com/PCN</u> sign into myMICROCHIP to open the myMICROCHIP home page, then select a profile option from the left navigation bar.

To opt out of future offer or information emails (other than product change notification emails), click here to go to <u>microchipDIRECT</u> and login, then click on the "My account" link, click on "Update profile" and un-check the box that states "Future offers or information about Microchip's products or services."

KSRA-25BPKT420 - CCB 3467 Initial Notice: Qualification of a new lead frame with double ring plating on paddle for selected Atmel products of 58.85K wafer technology available in 48L TQFP (7x7x1.0mm) package at ASE assembly site using palladium coated copper with gold flash (CuPdAu) bond wire

Affected Catalog Part Numbers (CPN)

ATSAM4LC2AA-AU ATSAM4LC2AA-AU ATSAM4LC4AA-AU ATSAM4LC4AA-AU ATSAM4LS2AA-AU ATSAM4LS2AA-AU ATSAM4LS4AA-AU